CHMER

High Precision Linear Drive Laser Cutting Machine





PL Series

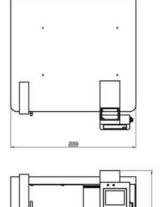
http://www.chmer.com/tw

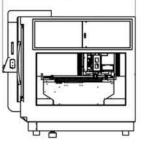
Floor Layout

PL4848

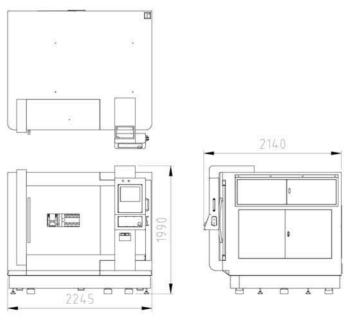
PL6060



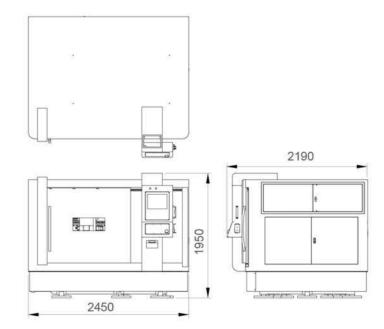








PL10080



Standard Model

Item	Unit	PL4848	PL6060	
X,Y Axis	m.m	480 x 480	600 x 600	
Z Axis	m m	120	120	
Processing Size	m m	480 x 480	600 x 600	
Max.Work Piece Weight	Kg	100	100	
Net Weight	Kg	2100	2200	
Max. X&Y Axis Operating Speed	m/min	15	18	
Power Consumption	kVA	Max. 6		
Outsize Dimensions [WxDxH]	mm	1650x2250x2000	2050x2300x2050	
Cutting Thickness	mm	0.05 - 1.0	0.05 - 1.0	

Item	Unit	PL6868	PL6880	PL8080	PL10080
X,Y Axis	mm	680x680	680x800	800x800	1000x800
Z Axis	mm	120			
Processing Size	mm	680x680	680x800	800x800	1000x800
Max.Work Piece Weight Kg		120			
Net Weight	Kg	2250	2350	2400	2500
Max. X&Y Axis Operating Speed	m/min	20	20	25	30
Power Consumption	kVA	Max	. 8	Max	. 24
Outsize Dimensions [WxDxH]	mm	2245 x 2150 x 1990	2245 x 2150 x 1990	2245 x 2150 x 1990	2450 x 2190 x 1950
Cutting Thickness	mm		0.05 -	2.0	

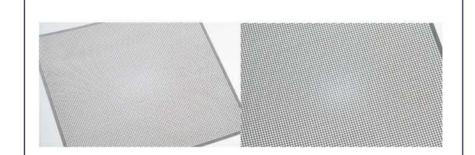
Note: Cutting thickness differs from various laser source.



^{*} Manufacture reserves the right to modify design, specification and machine structure for continuous research and improvement.

LC Series

FEATURE



Specially Designed For High Reflective Material And Complicate Machining

This machine is designed especially for high reflective and sensitive material. When encountering sharp and narrow angle, shorter pulse time and frequency parameter according to high peak value can be chosen to make nice surface and smaller heat-affected area.



Equipped with patented in-house linear motor featuring with high responsive, zero vibration, zero backlash, long life, zero maintenance to provide excellent working accuracy.



German PRECITEC **Cutting Head-MiniCutter**

High responsive control system and adjustable focal length ensures stability of complicate shape workpiece during cutting. Light structure design enables severe bending workpiece cutting resulting in optimum work art. Quick-release protective lens are easy for changing and wiping.



German PRECITEC Cutting Head-FineCutter

Real time monitor for cutting process through coaxial version. Equipped with adjustable lighting device in eyesight area. Maximum cutting power at 500W. Suitable for UKP laser. High quality optics components allows workpiece gap at minimum of 10µm width.



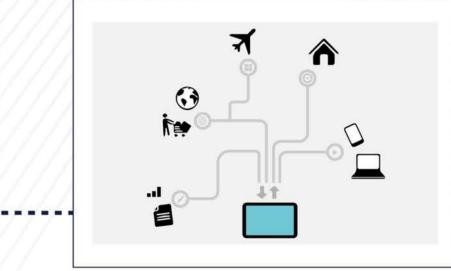
Patented Air Filter

Patented ionogen dust collector with HEAP filter effectively filtrates all kinds of suspending smoke and gas to keep work area air at highest quality.



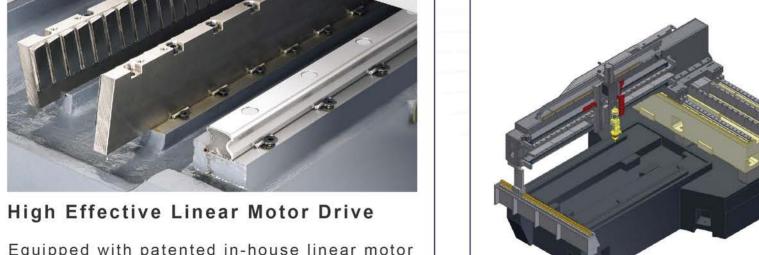
German IPG Optical Fiber Laser Source

IPG is the largest laser source provider on current market. Advantages of IPG optical fiber laser source are speedy raising/lowering power and working under continuous and high peak power pulse. Different from traditional laser, shaping pulse cutting reduces slag and heat affected zone (HAZ) at maximum.



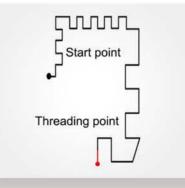
Remote Control & Internet of Machine System (Optional)

Brand new "remote control & internet of machine system" brings you the experience of high technology to control machine with mobile device at hand without standing in front of machines all the time. Innovative smart functions builds complete mobile management environment for you to step in smart machine new era.



Special Machine Structure

Design of gravity-drive and auxiliary FEA finite element analysis improves overhanging rail deflection problem and increases machine rigidity tremendously. Laser cutting head moving at high speed along workpiece axis provides high cutting efficiency.



Break Point Return

Restart of work at break point restores working status immediately avoids time wasting.



Initiative Parameter Setting Display

999 working parameters for different materials and thicknesses choices. All you need to do is to select suitable parameters, satisfactory working quality is within reach.

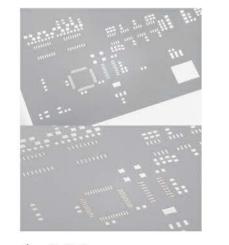
Samples & Application



Cooling Fin Material: Copper Thinckness: 0.8 mm Processing Time: 3min20s



◆ Iron Flip Chip Material: Silicon Steel Thinckness: 0.5 mm Processing Time: 1min45s



◆ PCB

Material: Silicon Steel Thinckness: 0.2 mm Processing Time: 22min43s